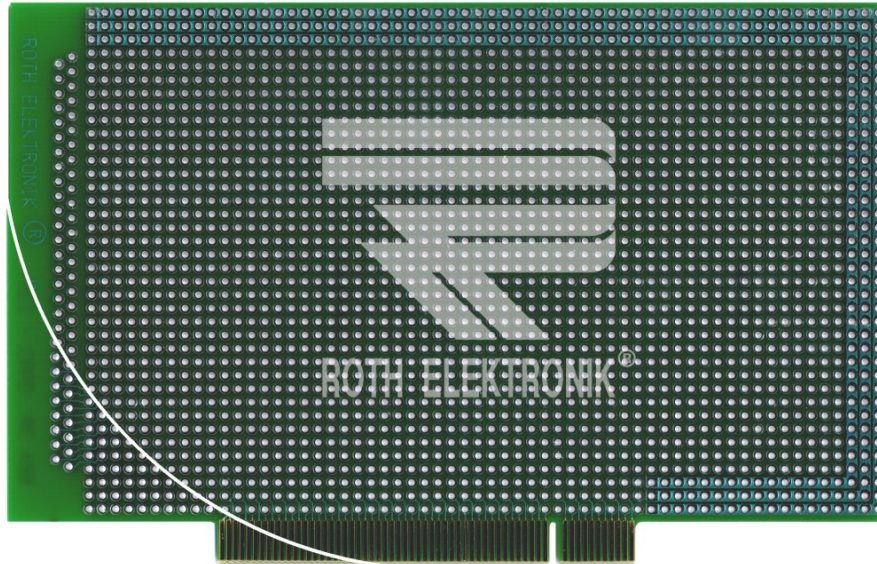


PCI-BUS Experimental Board



RE430-LF



- EPOXY fibre-glass FR4 1.50 mm double-sided 35 µm CU (pth)
- hot air leveling (HAL-leadfree)
- soldering islands 2.00 mm Ø
- hole dia 1.0 mm
- grid 2.54 x 2.54 mm
- 3 potential paths
- solder and component side with solder stop mask
- plug contacts: direct 2 x 11 two-pin and 2 x 49 two-pin, gold-plated 1.50 µm
- connecting possibility for D-subminiature plugs DIN 41652
- 9.25 and 37 poles
- solder bath proof: 260° C. > 50 Sek.
- size 167.61 x 106,68 mm